SP-TMEP70

Technical Data Sheet

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Thermoplastic Modified Epoxy Resin

SP-TMEP70 is a dissolution product that consists of 70% thermoplastic-modified epoxy resin dissolved in 30% Bisphenol F-based liquid epoxy resin.

The benefits from the use of thermoplastic modified epoxy resins include (but are not limited to) improvements in fracture toughness, peel strength, and strain to failure. Unlike rubber-modified epoxy materials, these thermoplastic-modified epoxy resins help with the aforementioned properties without sacrificing glass transition temperature and adhesion.

Commercially available modified thermoplastic epoxy resins have had limited use due to their high softening point, making them difficult to incorporate into various products (such as adhesives, coatings and prepregs). Now, a series of thermoplastic-modified epoxy resins are available with a range of softening points to balance the ease of incorporation with the performance of the end product.

These thermoplastic modified epoxy resins may be cured using conventional curing technologies for single component systems (e.g. with dicyandiamide).

Specific Physical Form:	Solid Flake or Granule
Color:	Tan
Shelf Life:	3 Years

Typical Properties:

Specific Gravity:	1.20 g/cc
Epoxy Equivalent Weight:	520 - 685 g/eq.
Molecular Weight of Polymeric Portion	Mn = 6,000 - 12,000 g/mol Mw = 25,000 - 35,000 g/mol

Disclaimer:

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